Appl. No. 10/608,011 Amendment dated February 16, 2007 Reply to Office Action of November 16, 2006

Amendments to the Specification (Abstract)

Please amend the Abstract of the Disclosure as follows:

The present invention concerns optical transmission units and provide simply structured and highly reliable optical modules or optical transmission units which are especially suitable for a low cost optical transmission system.

TheA semiconductor optical device according to the present invention, which is mounted junction down on a mounting plate via the solder metal of the mounting plate. The, is characterized in that the electrode of the semiconductor optical device facing the mounting plate is partially coated with a dielectric film and the dielectric film is in contact with the solder metal on the mounting plate.

The present invention can suppress The reaction between the semiconductor optical device and the solder metal of the mounting plate can be suppressed without deteriorating the thermal conductivity between the semiconductor optical device and the mounting plate. Therefore, it is possible to improveraise the reliability of the semiconductor optical device mounted in the junction down form since diffusion of the solder metal into the semiconductor can be prevented.